



US00D504335S

(12) **United States Design Patent** (10) **Patent No.:** **US D504,335 S**  
**Stevenson et al.** (45) **Date of Patent:** **\*\* Apr. 26, 2005**

(54) **SENSOR HOUSING** 6,637,933 B1 \* 10/2003 Liao ..... 374/170  
 6,811,308 B2 \* 11/2004 Chapman et al. .... 374/208

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(73) Assignee: **Building Automation Products, Inc.**, Gays Mills, WI (US)

(\*\*) Term: **14 Years**

(21) Appl. No.: **29/197,111**

(22) Filed: **Jan. 9, 2004**

(51) **LOC (7) Cl.** ..... **10-04**

(52) **U.S. Cl.** ..... **D10/57**

(58) **Field of Search** ..... D10/57, 60; 374/209, 374/208, 170, 155, 142, 141, 183

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

3,946,613 A	*	3/1976	Silver	.....	374/208
D264,190 S	*	5/1982	Muller	.....	D10/57
D314,155 S		1/1991	Toivonen		
D333,792 S		3/1993	Odom, Jr.		
D361,947 S		9/1995	Cochran et al.		
D364,350 S		11/1995	Pasquarrette et al.		
D366,429 S		1/1996	Dexter et al.		
D378,900 S		4/1997	de Sieyes et al.		
D381,279 S		7/1997	Ingebritson et al.		
D390,134 S		2/1998	Ingebritson et al.		
D390,482 S		2/1998	Pasquarrette		
D393,214 S		4/1998	Ingebritson et al.		
D403,972 S		1/1999	Gaskell et al.		
D435,224 S		12/2000	King et al.		
D446,132 S		8/2001	Pickens		
D447,963 S		9/2001	Ingebritson		
6,379,039 B1	*	4/2002	Tseng	.....	374/170
D460,923 S		7/2002	Chen		
D467,188 S		12/2002	Lui		

**OTHER PUBLICATIONS**

Author: Building Automation Products, Inc; Title: "BAPI Printed Catalog"; Title of the item: Catalog; Date of publication: Jan., 1999; Relevant pages: pp. A5-A16, B5-B16, C5-C7, D5-D14, and G5; Publisher; Building Automation Products, Inc; Where published: Cross Plains, Wisconsin, USA.

\* cited by examiner

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(57) **CLAIM**

The ornamental design for a sensor housing, as shown and described.

**DESCRIPTION**

FIG. 1 is a top, front and right side perspective view of a temperature and humidity sensor housing in accordance with our new design;

FIG. 2 is a front elevation view of the temperature and humidity sensor housing shown in FIG. 1;

FIG. 3 is a top plan view of the temperature and humidity sensor housing shown in FIG. 1;

FIG. 4 is a bottom plan view of the temperature and humidity sensor housing shown in FIG. 1;

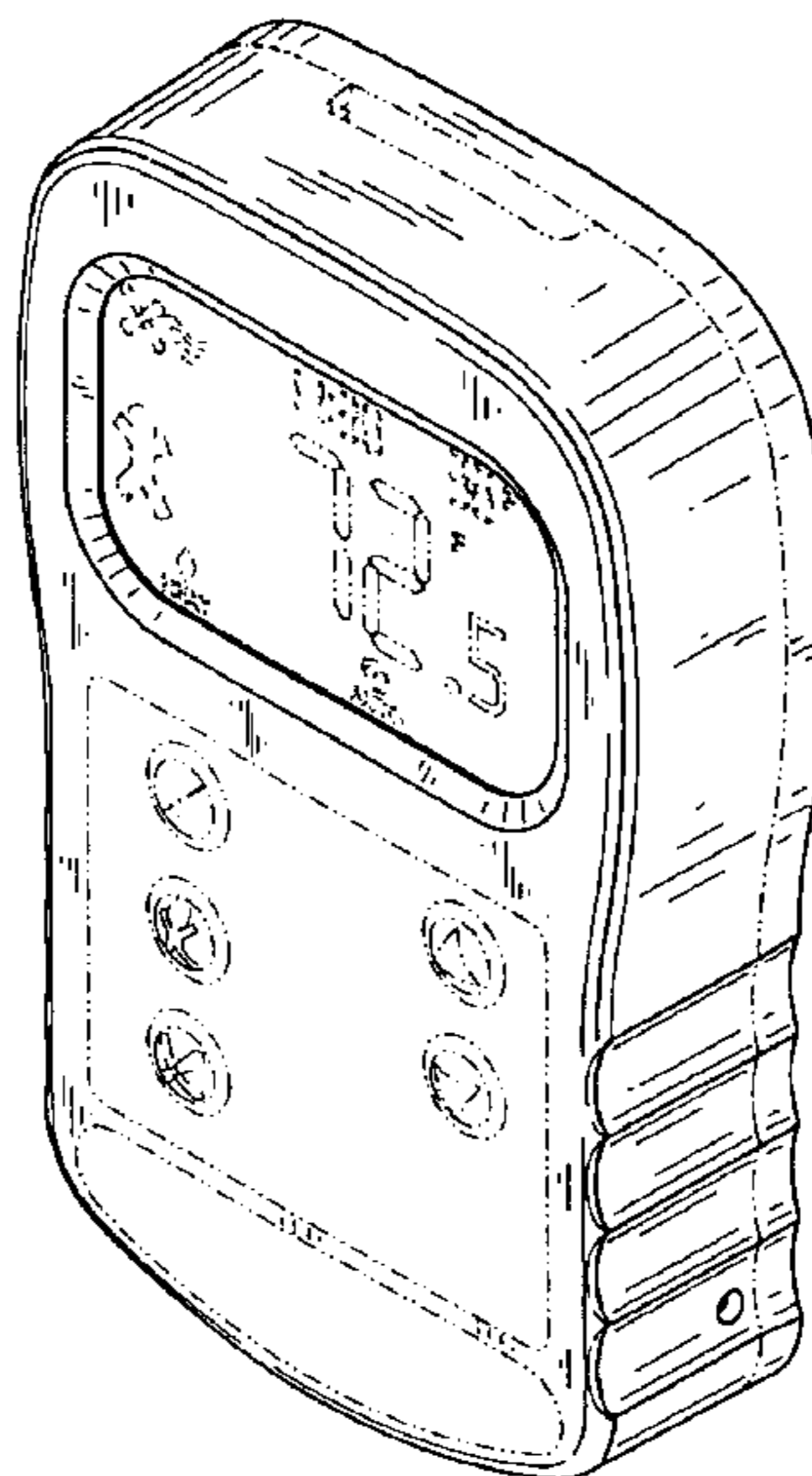
FIG. 5 is a right side elevation view of the temperature and humidity sensor housing shown in FIG. 1; and,

FIG. 6 is a left side elevation view of the temperature and humidity sensor housing shown in FIG. 1.

The rear of the sensor housing does not comprise any portion of the invention, and hence is not shown in the drawings.

The broken line showings are for illustrative purposes only and form no part of the claimed design.

**1 Claim, 3 Drawing Sheets**



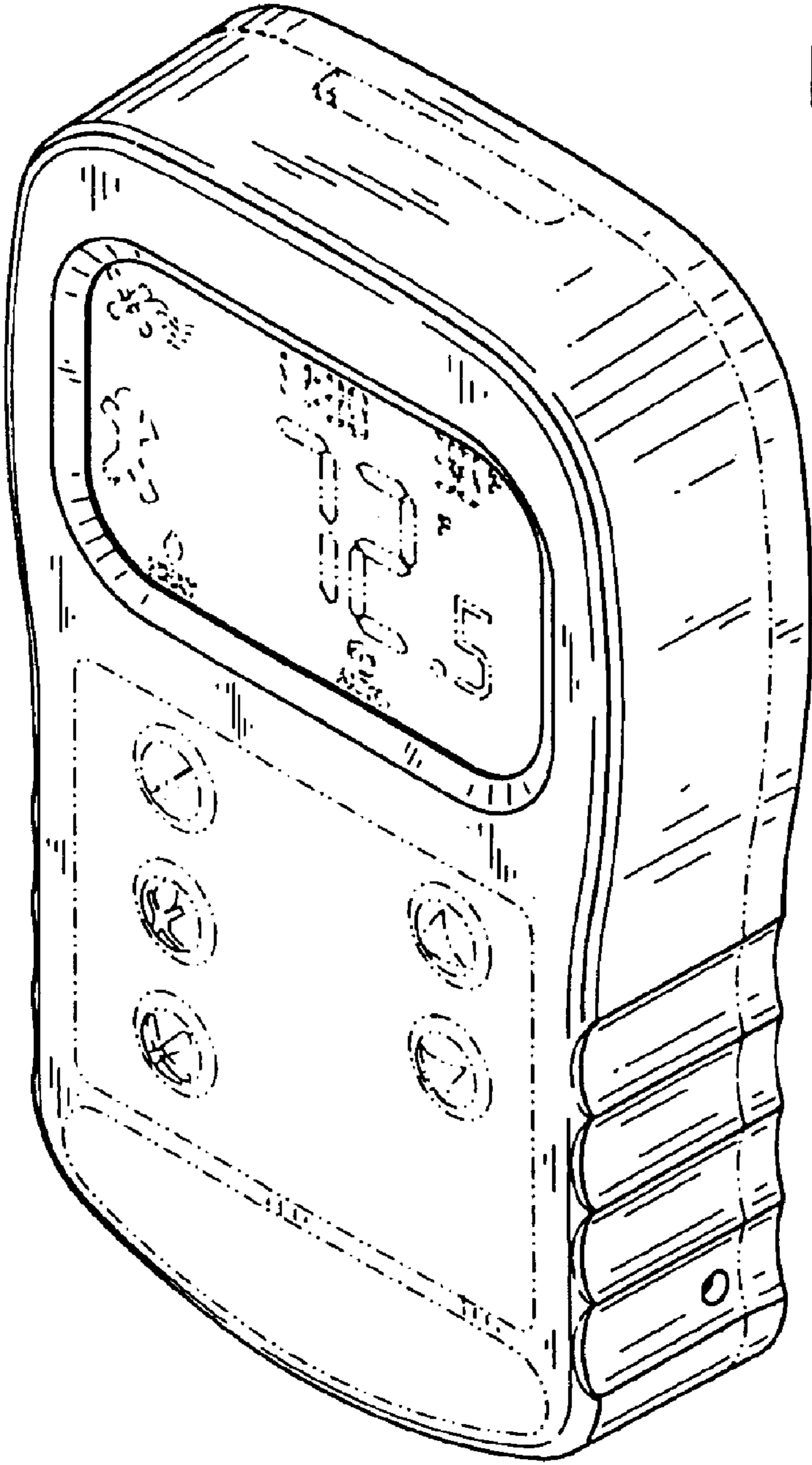


FIG. 1

FIG. 2

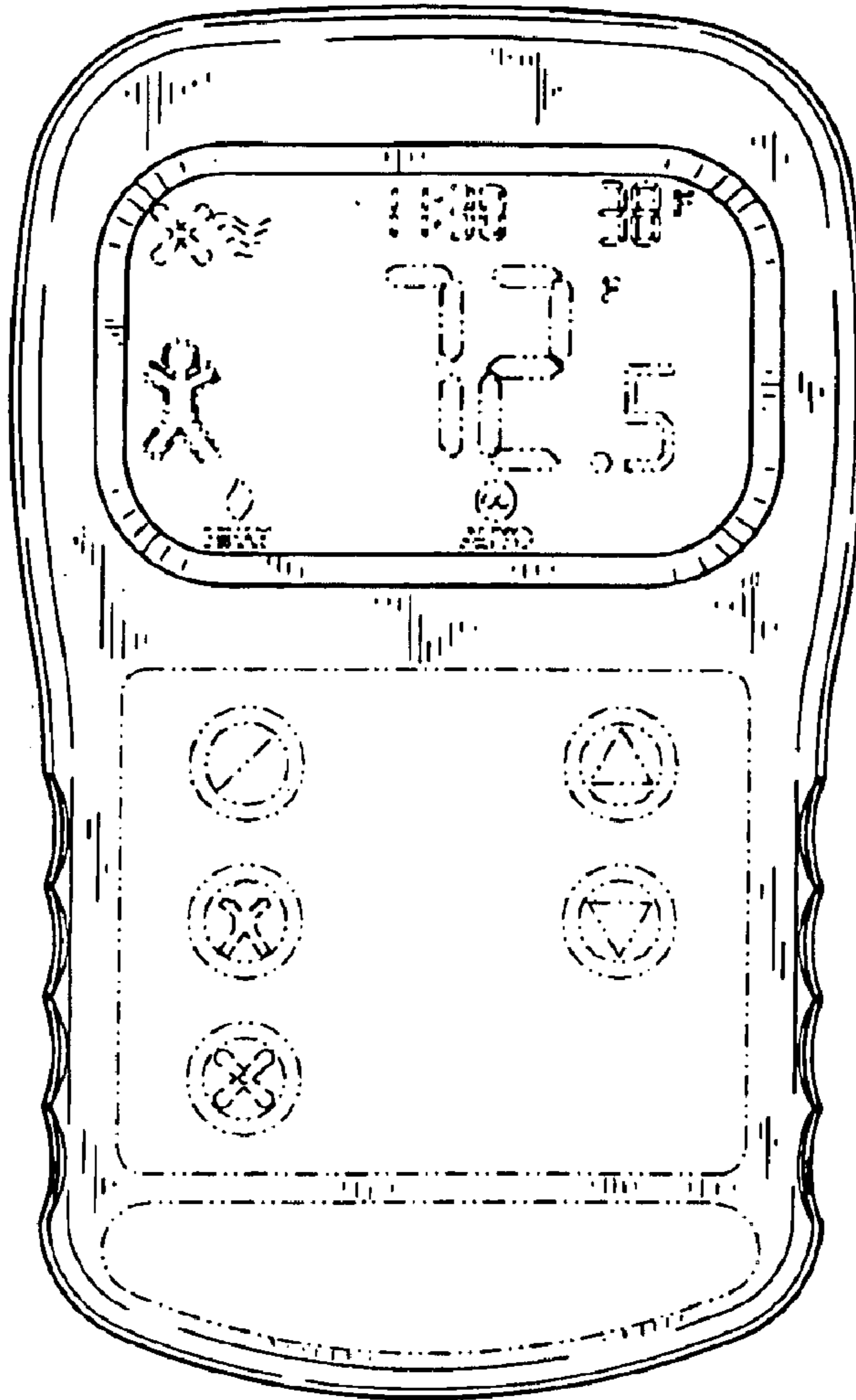


FIG. 3

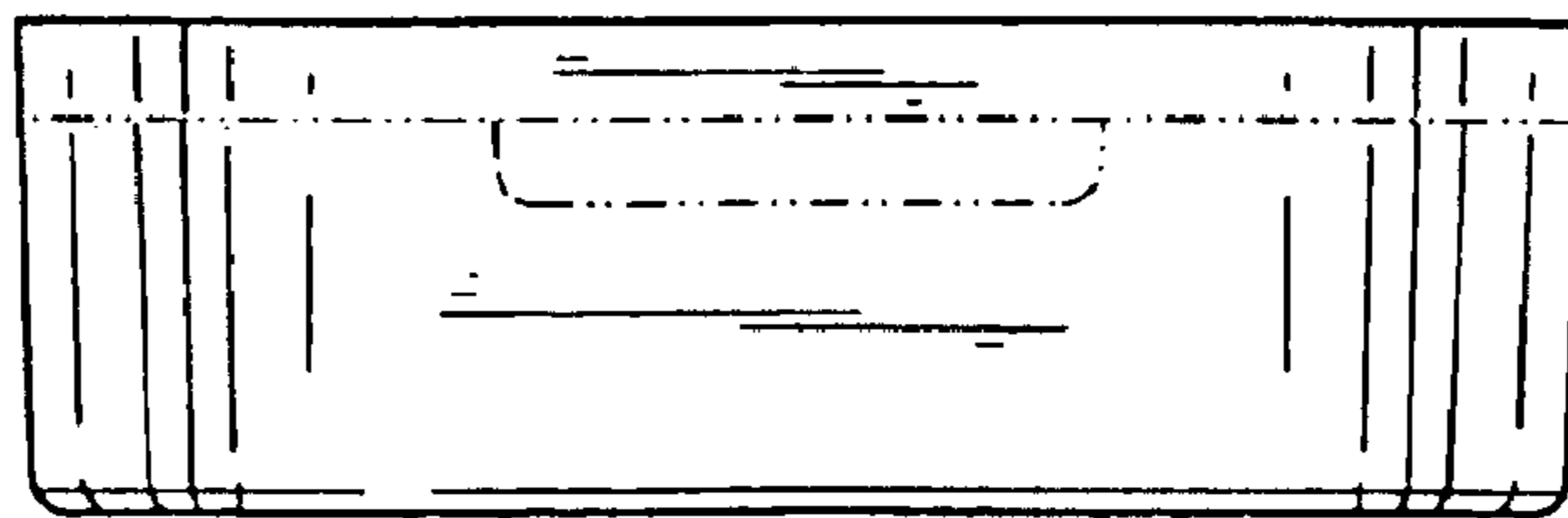
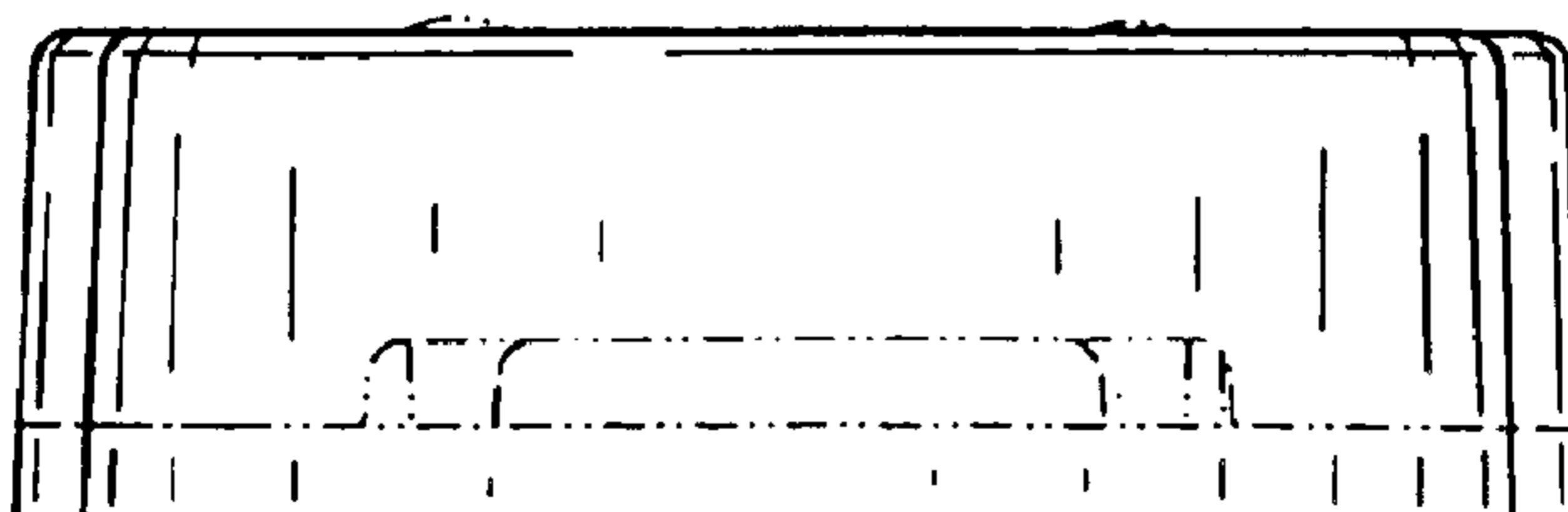


FIG. 4



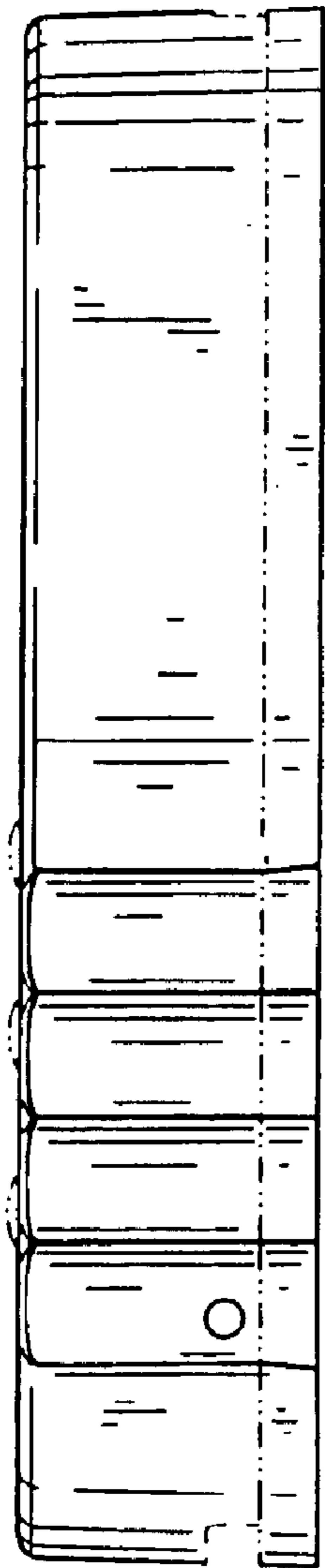


FIG. 5

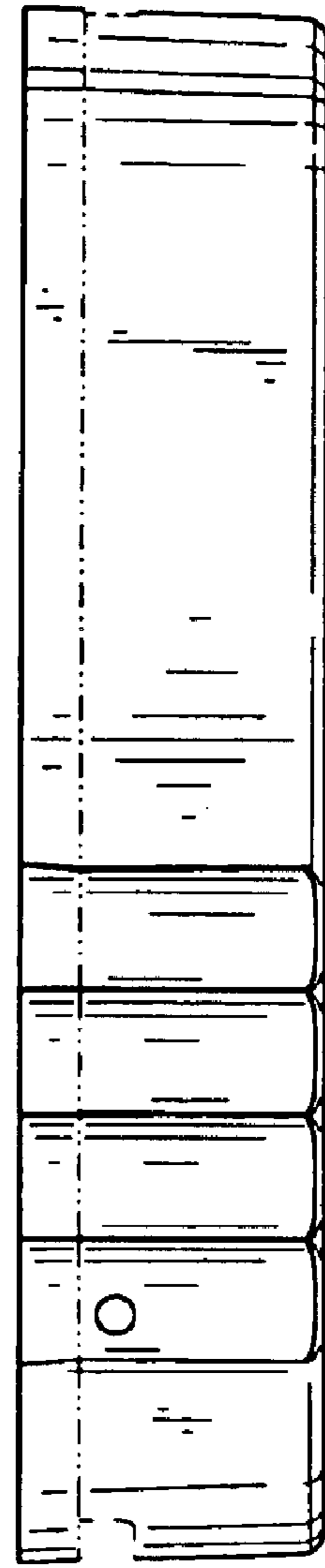


FIG. 6